## NCE N-Channel Enhancement Mode Power MOSFET

## **Description**

The NCE30H14K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> =30V,I<sub>D</sub> =140A

 $R_{DS(ON)}$  <3.0m $\Omega$  @  $V_{GS}$ =10V

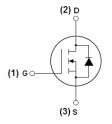
 $R_{DS(ON)} < 3.6 m\Omega$  @  $V_{GS} = 4.5 V$ 

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

### **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED! 100% ΔVds TESTED!



#### Schematic diagram



Marking and pin assignment



TO-252-2L top view

**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30H14K	NCE30H14K	TO-252-2L	-	-	-

## Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	140	Α
Drain Current-Continuous(T <sub>C</sub> =100℃)	I <sub>D</sub> (100℃)	99	Α
Pulsed Drain Current	I <sub>DM</sub>	400	Α
Maximum Power Dissipation	P <sub>D</sub>	130	W
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	400	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	°C

### **Thermal Characteristic**

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	R <sub>eJC</sub>	1.25	°C/W
---	------------------	------	------



# Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

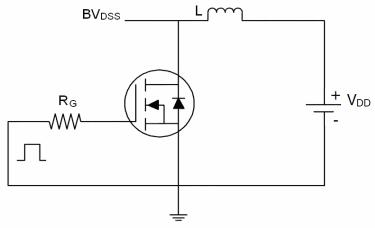
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	•		•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA 30		-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	<u>.</u>					
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1	1.6	2.5	V
Drain Source On State Decistance	В	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	2.5	3.0	m0
ain-Source On-State Resistance R <sub>DS(C</sub>		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	2.9	3.6	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	50	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C <sub>lss</sub>	\/ -45\/\/ -0\/		3780		PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0V, F=1.0MHz		448		PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVITZ		410		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	12	-	nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V	-	16	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_L$ =0.75 $\Omega$ , $R_{GEN}$ =3 $\Omega$	-	42	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Qg			80		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V,I <sub>D</sub> =20A		12.4		nC
Gate-Drain Charge	Q <sub>gd</sub>			18.3		nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is	-		-	140	Α
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, I <sub>F</sub> =20A	-	58	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	115	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD				
		•				

#### Notes:

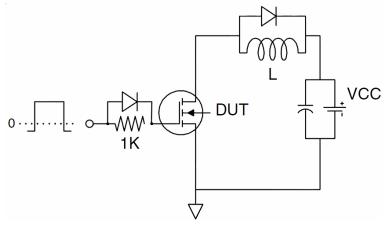
- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature}.$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}$ C,V<sub>DD</sub>=15V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$

## **Test circuit**

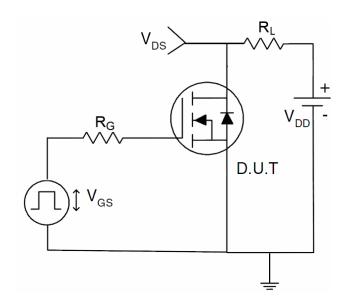
## 1) E<sub>AS</sub> test Circuits



## 2) Gate charge test Circuit:

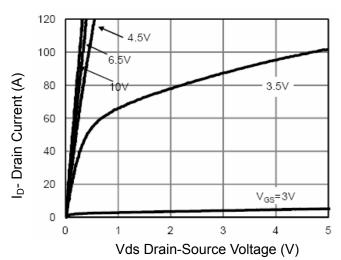


## 3) Switch Time Test Circuit:

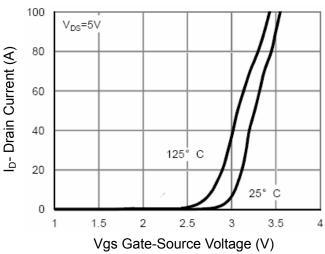




## **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

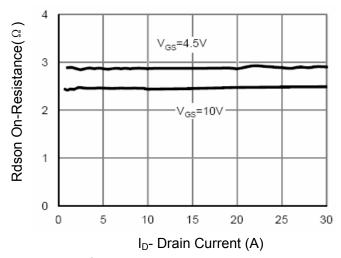
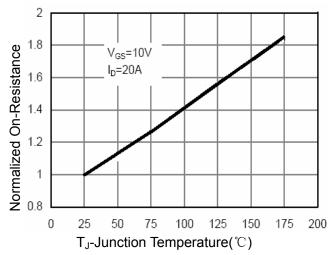


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

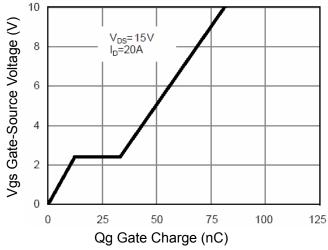


Figure 5 Gate Charge

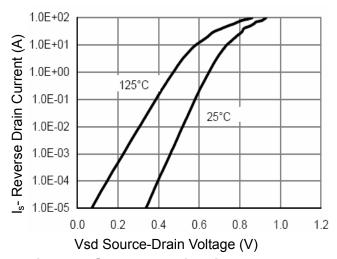


Figure 6 Source- Drain Diode Forward



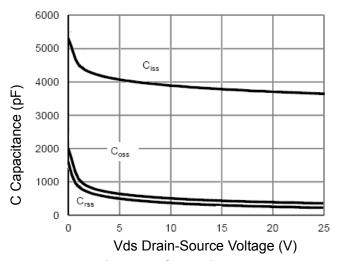
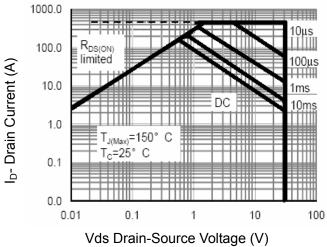


Figure 7 Capacitance vs Vds



**Figure 8 Safe Operation Area** 

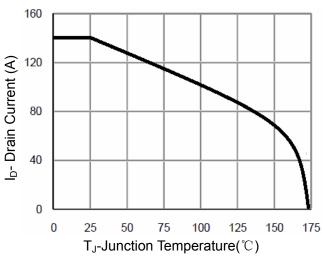


Figure 9 Current De-rating

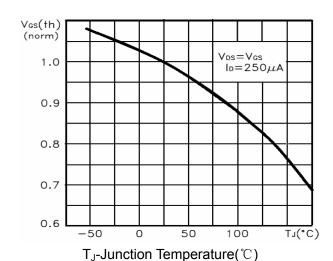
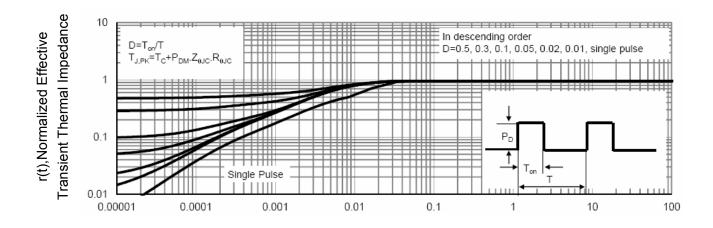


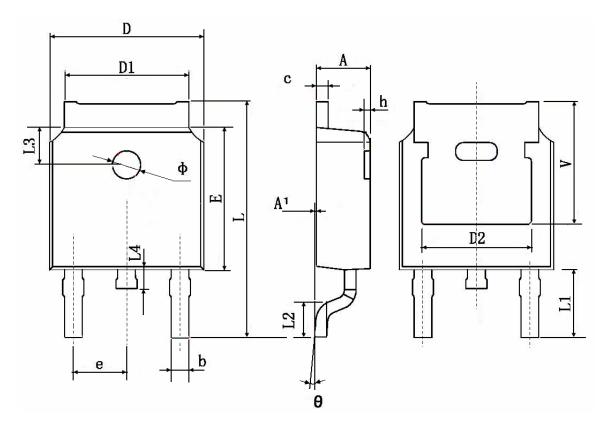
Figure 10 V<sub>GS(th)</sub> vs Junction Temperature



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

# **TO-252 Package Information**



Comple of	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.83	4.83 TYP.		TYP.	
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063	TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		

## Attention:

- Any and all NCE power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE power representative nearest you before using any NCE power products described or contained herein in such applications.
- NCE power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE power products described or contained herein.
- Specifications of any and all NCE power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE power product that you intend to use.
- This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by NCE Power manufacturer:

Other Similar products are found below:

IRFD120 JANTX2N5237 BUK455-60A/B MIC4420CM-TR VN1206L NDP4060 SI4482DY IPS70R2K0CEAKMA1 SQD23N06-31L-GE3
TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7
DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE